HEATFLOW-SIL

HEATFLOW-SIL TCS-2010US is an extremely conformable, low modules silicone polymer filled with special conductive filler that excellent heat conductivity and flame retardant UL94V-O level together with good electrical properties.



HEATFLOW-SIL TCS-2010US is specially designed for applications requiring maximum heat transfer away through metal chassis or heat spreader and a minimum pressure on components.

HEATFLOW-SIL TCS-2010US is a thermally conductive silicone supplied on a thin PET film carrier or glass fiber allowing for easy material handling and enhanced puncture, shear, and tear resistance.

Special feature

- Ultra soft and flexible elastic silicone conformable pads
- Any thickness are available
- Good heat conductivity
- Excellent electrical insulation properties
- Excellent flame retardant as UL94V-O level
- Easy for cutting and mounting

Application

- Areas where heat needs to be transferred away to the frame chassis or other type of heat spreader
- Between a CPU and a heat spreader
- Between a CD ROM and a heat spreader
- Between a semiconductor and heat sink
- Replacement for messy grease

Products supply

HEATFLOW-SIL TCS-2010US is available in standard size and custom width and length Standard Size (mm) : 200×200, 210×300

Force VS. Deflection Curve



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Thermal Interface Material LY-TCS-2010US

PROPERTIES

Properties		Value	Test Method
Thickness	(mm)	0.5 ~ 10	ASTM D 374
Color		White	Visual
Reinforcement			
Hardness 00)	(Shore	5	ASTM D 2240
Specific Gravity	(g/cൺ)	1.6	ASTM D 792
Continue Use	(°C)	-60 ~ +200	
Thermal Conductiv (w/m.K)	ity 10psi	1.0	ASTM D 5470
Dielectric Constant		5.5	ASTM D 150
Dielectric Breakdown	kV AC	>6	ASTM D 149
Volume Resistivity	ohm Meter	10 ¹³	ASTM D 257

B) How To Order (Part Number)

TCS - 2010<mark>US</mark> - F A1 - 5.0 - 100+200

